



# BCR16CM-12LB

Triac

Medium Power Use

(The product guaranteed maximum junction temperature of 150°C)

REJ03G0457-0300

Rev.3.00

Nov 30, 2007

## Features

- $I_{T(RMS)}$  : 16 A
- $V_{DRM}$  : 600 V
- $I_{FGT}$ ,  $I_{RGT}$ ,  $I_{RGT III}$  : 30 mA (20 mA)<sup>Note6</sup>
- Non-Insulated Type
- Planar Passivation Type

## Outline

RENESAS Package code: PRSS0004AA-A  
(Package name: TO-220)



1. T<sub>1</sub> Terminal
2. T<sub>2</sub> Terminal
3. Gate Terminal
4. T<sub>2</sub> Terminal

## Applications

Contactless AC switch, light dimmer, electronic flasher unit, control of household equipment such as TV sets, stereo systems, refrigerator, washing machine, infrared kotatsu, carpet, electric fan, solenoid driver, small motor control, copying machine, electric tool, electric heater control, and other general purpose control applications

## Warning

1. Refer to the recommended circuit values around the triac before using.
2. Be sure to exchange the specification before using. Otherwise, general triacs with the maximum junction temperature of 125°C will be supplied.

## Maximum Ratings

Parameter	Symbol	Voltage class	Unit
		12	
Repetitive peak off-state voltage <sup>Note1</sup>	$V_{DRM}$	600	V
Non-repetitive peak off-state voltage <sup>Note1</sup>	$V_{DSM}$	720	V



## BCR16CM-12LB (The product guaranteed maximum junction temperature of 150°C)

Parameter	Symbol	Ratings	Unit	Conditions
RMS on-state current	$I_{T(RMS)}$	16	A	Commercial frequency, sine full wave 360° conduction, $T_c = 125^\circ\text{C}$ <sup>Note3</sup>
Surge on-state current	$I_{TSM}$	170	A	60Hz sinewave 1 full cycle, peak value, non-repetitive
$I^2t$ for fusing	$I^2t$	121	$\text{A}^2\text{s}$	Value corresponding to 1 cycle of half wave 60Hz, surge on-state current
Peak gate power dissipation	$P_{GM}$	5.0	W	
Average gate power dissipation	$P_{G(AV)}$	0.5	W	
Peak gate voltage	$V_{GM}$	10	V	
Peak gate current	$I_{GM}$	2	A	
Junction temperature	$T_j$	- 40 to +150	°C	
Storage temperature	$T_{stg}$	- 40 to +150	°C	
Mass	—	2.0	g	Typical value

Notes: 1. Gate open.

## Electrical Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test conditions	
Repetitive peak off-state current	$I_{DRM}$	—	—	2.0	mA	$T_j = 150^\circ\text{C}$ , $V_{DRM}$ applied	
On-state voltage	$V_{TM}$	—	—	1.5	V	$T_c = 25^\circ\text{C}$ , $I_{TM} = 25\text{ A}$ , Instantaneous measurement	
Gate trigger voltage <sup>Note2</sup>	I	$V_{FGTI}$	—	—	1.5	V	$T_j = 25^\circ\text{C}$ , $V_D = 6\text{ V}$ , $R_L = 6\ \Omega$ , $R_G = 330\ \Omega$
	II	$V_{RGTI}$	—	—	1.5	V	
	III	$V_{RGTIII}$	—	—	1.5	V	
Gate trigger current <sup>Note2</sup>	I	$I_{FGTI}$	—	—	30 <sup>Note6</sup>	mA	$T_j = 25^\circ\text{C}$ , $V_D = 6\text{ V}$ , $R_L = 6\ \Omega$ , $R_G = 330\ \Omega$
	II	$I_{RGTI}$	—	—	30 <sup>Note6</sup>	mA	
	III	$I_{RGTIII}$	—	—	30 <sup>Note6</sup>	mA	
Gate non-trigger voltage	$V_{GD}$	0.2/0.1	—	—	V	$T_j = 125^\circ\text{C}/150^\circ\text{C}$ , $V_D = 1/2 V_{DRM}$	
Thermal resistance	$R_{th(j-c)}$	—	—	1.4	°C/W	Junction to case <sup>Note3 Note4</sup>	
Critical-rate of rise of off-state commutating voltage <sup>Note5</sup>	$(dv/dt)_c$	10/1	—	—	V/ $\mu\text{s}$	$T_j = 125^\circ\text{C}/150^\circ\text{C}$	

Notes: 2. Measurement using the gate trigger characteristics measurement circuit.

3. Case temperature is measured at the  $T_2$  tab 1.5 mm away from the molded case.

4. The contact thermal resistance  $R_{th(c-f)}$  in case of greasing is  $1.0^\circ\text{C/W}$ .

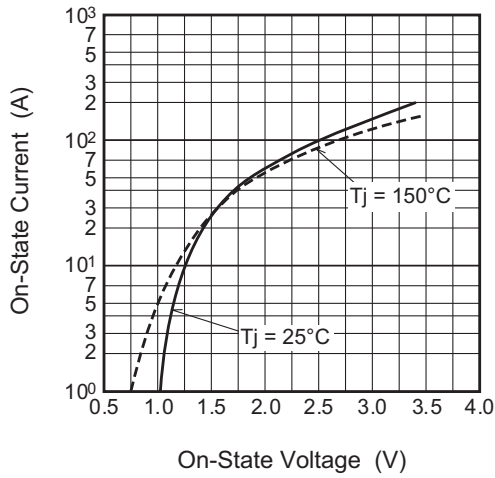
5. Test conditions of the critical-rate of rise of off-state commutating voltage is shown in the table below.

6. High sensitivity ( $I_{GT} \leq 20\text{ mA}$ ) is also available. ( $I_{GT}$  item: 1)

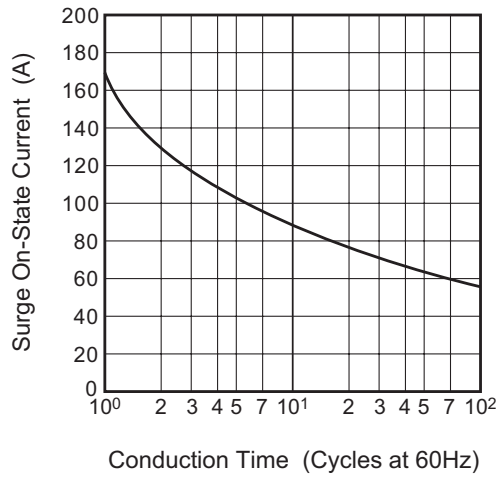
Test conditions	Commutating voltage and current waveforms (inductive load)
1. Junction temperature $T_j = 125^\circ\text{C}/150^\circ\text{C}$ 2. Rate of decay of on-state commutating current $(di/dt)_c = -8.0\text{ A/ms}$ 3. Peak off-state voltage $V_D = 400\text{ V}$	

Performance Curves

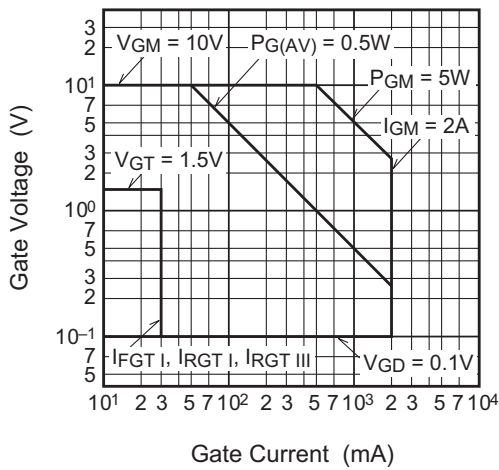
Maximum On-State Characteristics



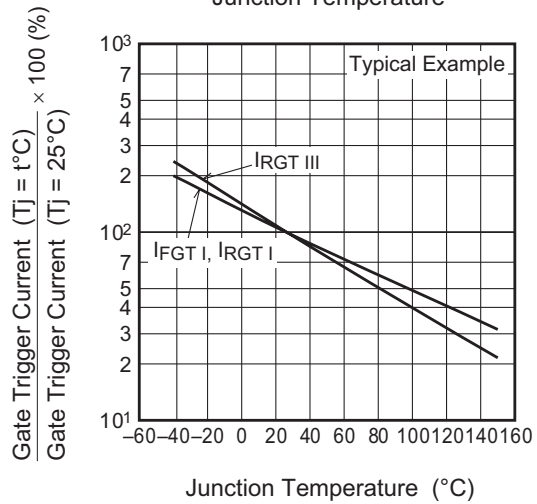
Rated Surge On-State Current



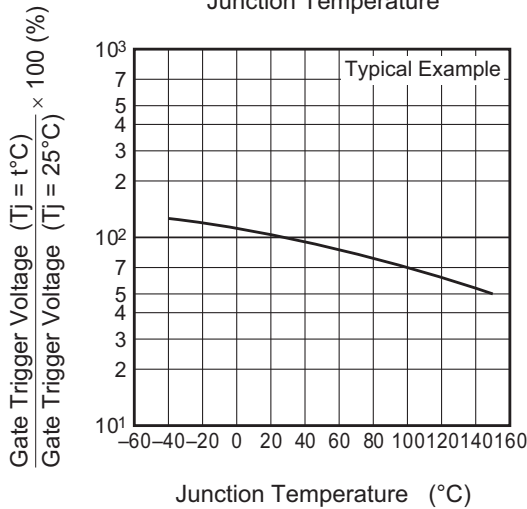
Gate Characteristics (I, II and III)



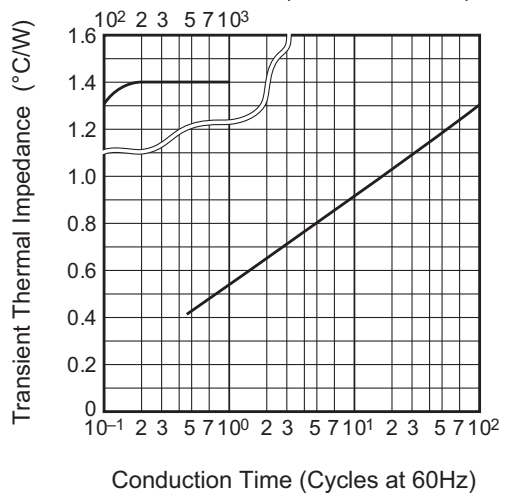
Gate Trigger Current vs. Junction Temperature



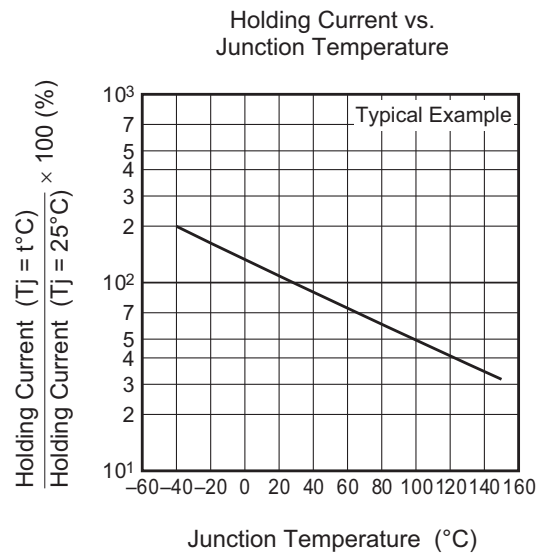
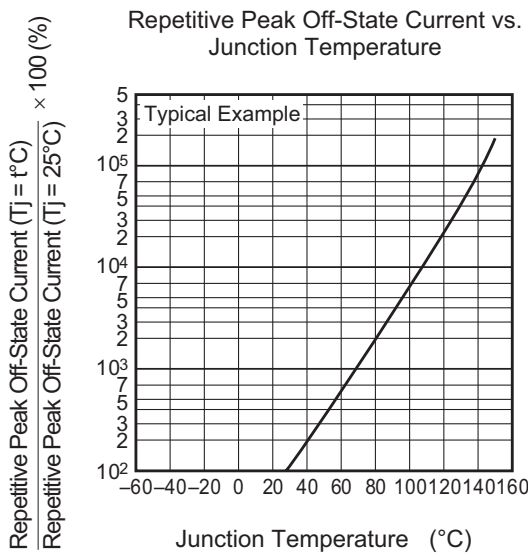
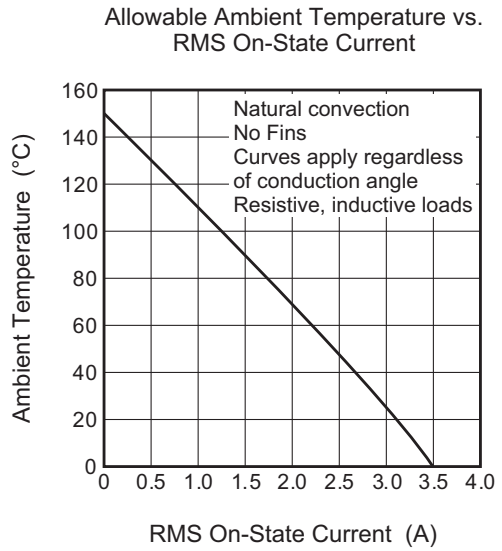
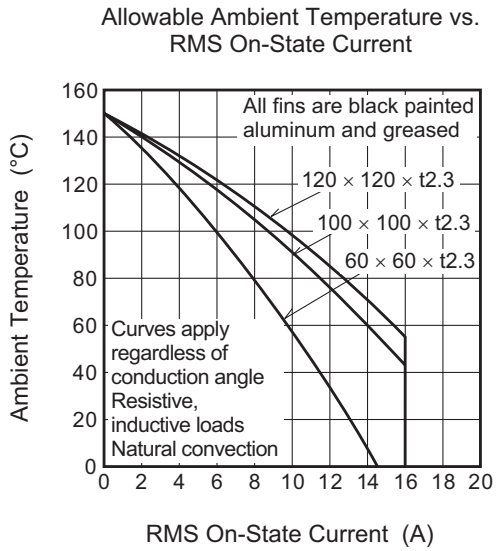
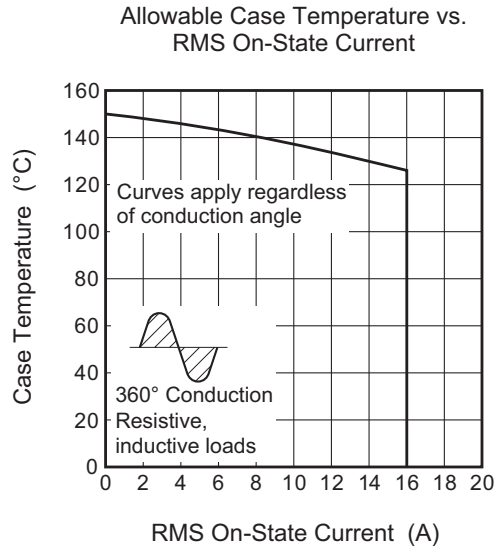
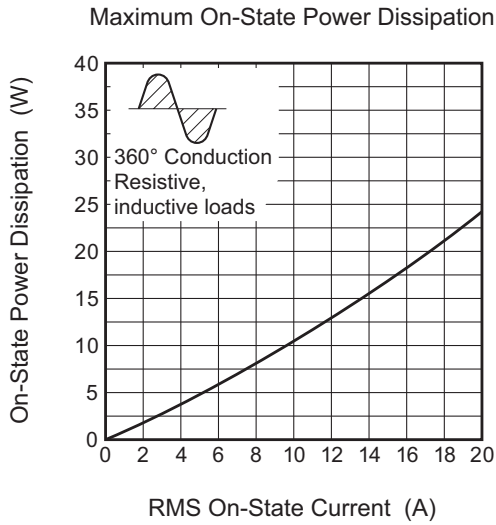
Gate Trigger Voltage vs. Junction Temperature



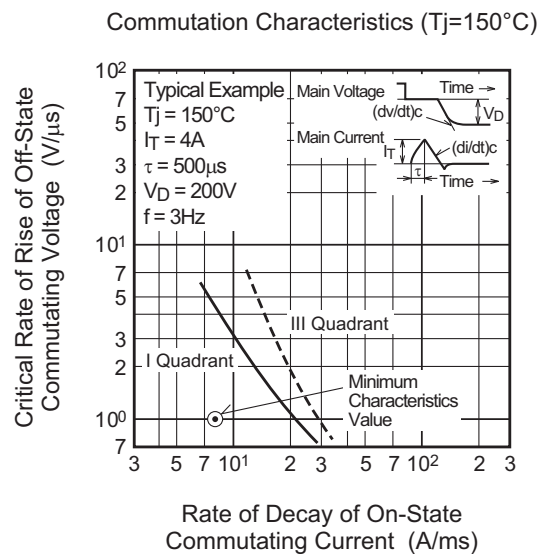
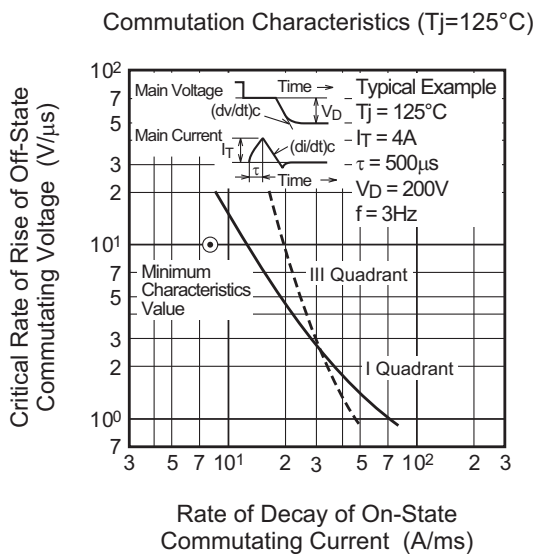
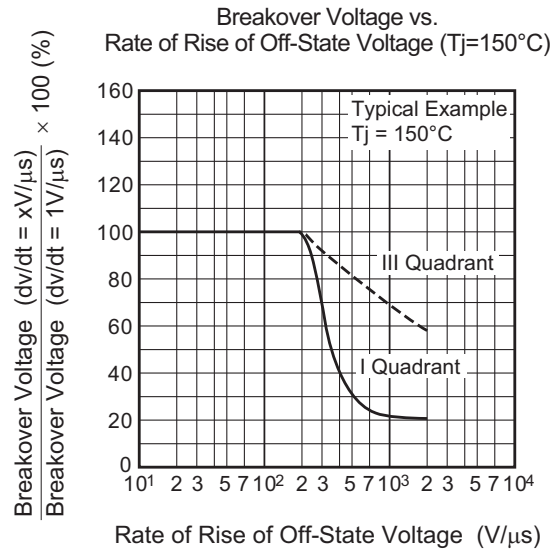
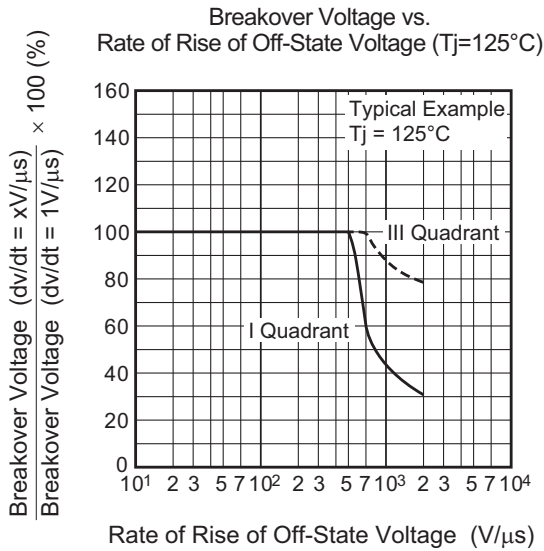
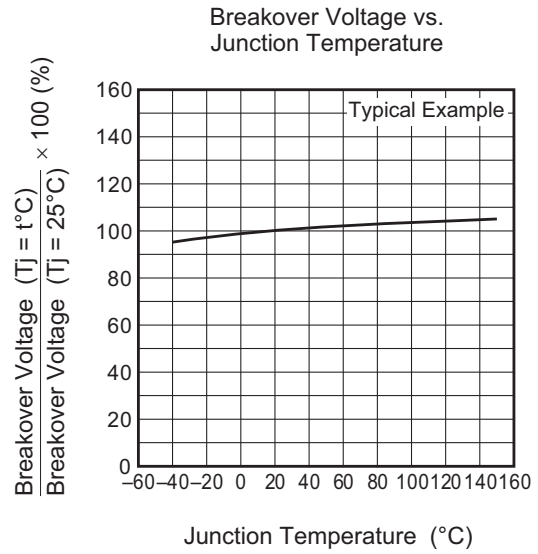
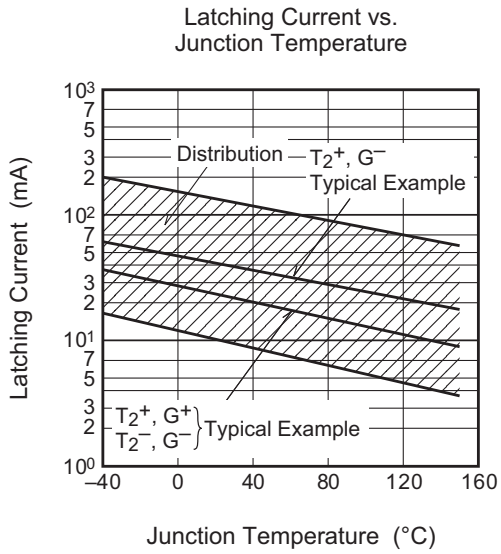
Maximum Transient Thermal Impedance Characteristics (Junction to case)



**BCR16CM-12LB (The product guaranteed maximum junction temperature of 150°C)**

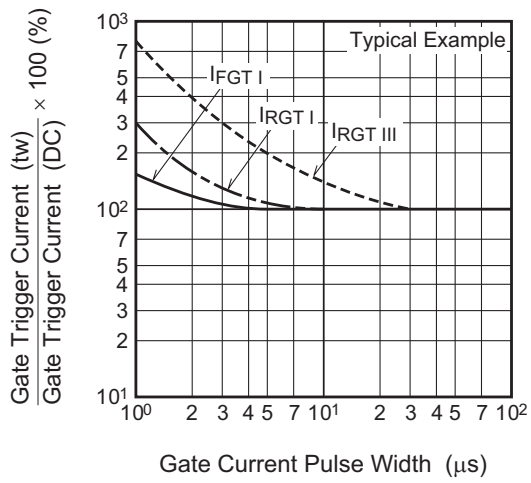


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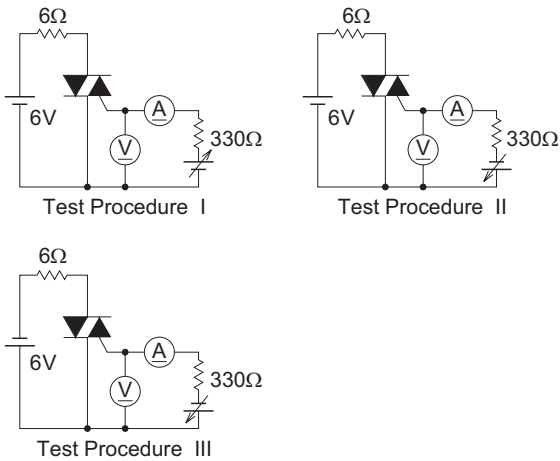


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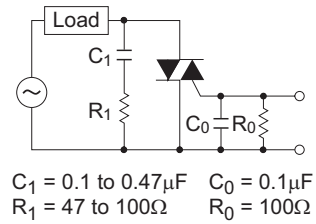
Gate Trigger Current vs. Gate Current Pulse Width



Gate Trigger Characteristics Test Circuits

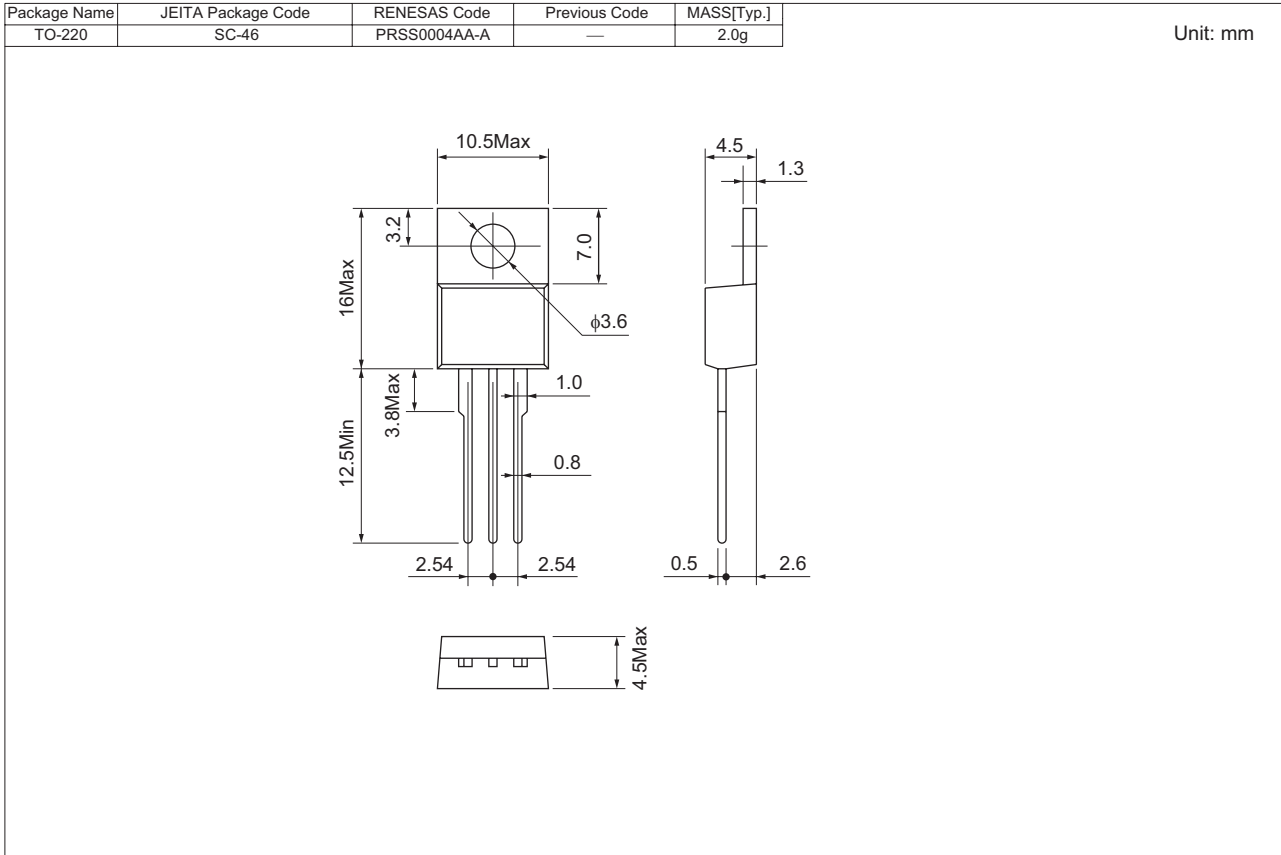


Recommended Circuit Values Around The Triac



**BCR16CM-12LB (The product guaranteed maximum junction temperature of 150°C)**

**Package Dimensions**



**Order Code**

Lead form	Standard packing	Quantity	Standard order code	Standard order code example
Straight type	Vinyl sack	100	Type name	BCR16CM-12LB
Lead form	Plastic Magazine (Tube)	50	Type name – Lead forming code	BCR16CM-12LB-A8

Note : Please confirm the specification about the shipping in detail.

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